

产品承认书

SPECIFICATION FOR APPROVAL

CUSTOMER:	
CUSTOMER P/N:	
CND-TEK P/N. :	G1804D
DESCRIPTION:	1000 BASE-T MAGNETICS MODULES
REF NO:	QTC-001
REV/NO:	V1.02
DATE:	2015/03/02

ATTACHMENT:
■ SPECIFICATION
■ SAMPLE Q'TY OF SAMPLES PCS

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			

CND-TEK

G1804D

1000 BASE-T MAGNETICS MODULES



V1.0.2
Feb 2, 2015

CND-TEK

深圳磁联达电子有限公司

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1. FEATURES:

1.1 Designed for long haul Gigabit Ethernet 1000 Base-T, full duplex applications.

1.2 Supports four pairs of category 5 UTP cable.

1.3 Cable interface for isolation and low common mode emissions

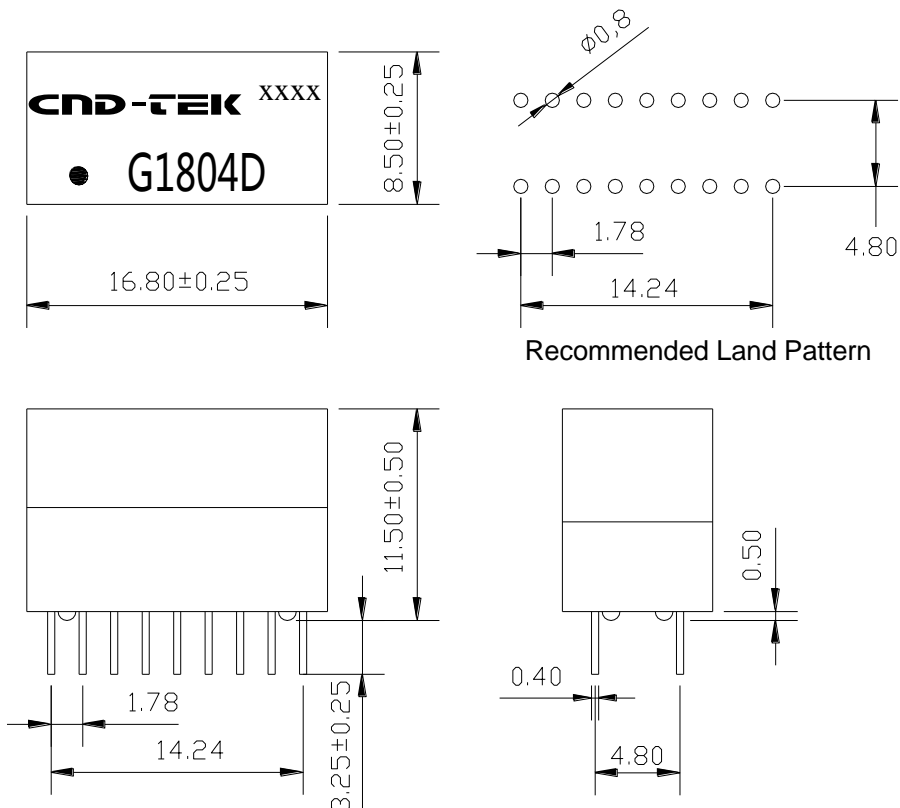
1.4 Compliant with IEEE 802.3ab standard for 1000 Base-T

1.5 Designed to support 1:1 Turns Ratio Transceivers.

1.6 Operating Temperature range: 0°C TO +70°C

1.7 Storage temperature range: -25°C TO +125°C

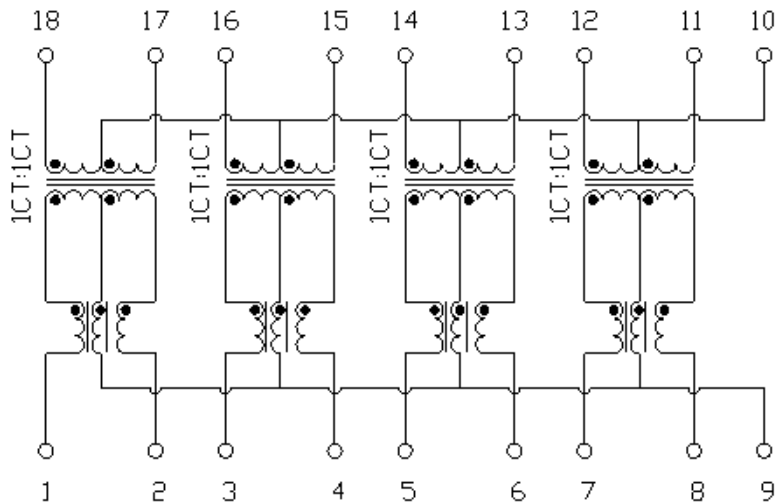
2. DIMENSIONS & MARKING



Note: 1、 Dimension: mm

2、 Unless otherwise specified, all tolerances are: ± 0.05 mm

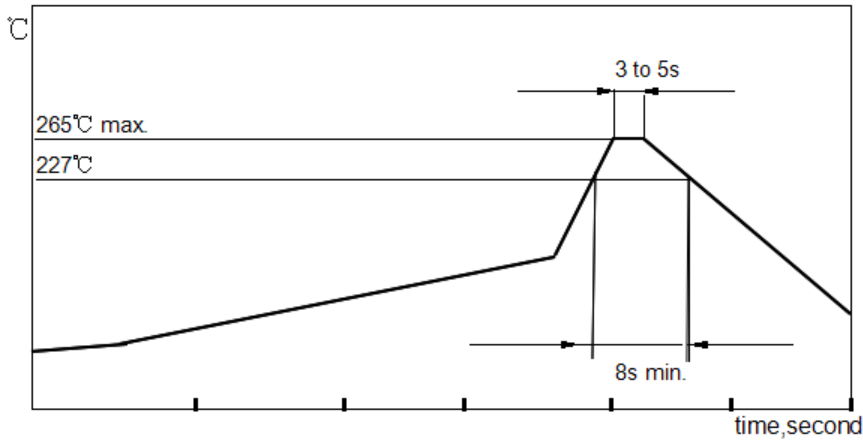
3. SCHEMATICS:



4. ELECTRICAL SPECIFICATIONS @25°C

- 4.1 OCL :** 350 μ H Min. @ 100 KHz, 100mV with 8mA DC Bias
- 4.2 Leakage Inductance:** 0.5 μ H Max. @ 100KHz, 0.2V
- 4.3 Cw/w:** 100 pF Max. @ 100KHz, 0.2V
- 4.4 DCR:** 1.20 Ω Max.
- 4.5 Turns Ratio(\pm 5%):** 1CT:1CT(TX), 1CT:1CT(RX)
- 4.6 Polarity** 1-18, 3-16, 5-14, 7-12 In-Phase
- 4.7 Insertion Loss:** -1.1 dB Max. @ 1-100MHz
- 4.8 Return Loss:** -18 dB Min. @ 0.5-30MHz
-15 dB Min. @ 40 MHz
-13 dB Min. @ 60 MHz
-11 dB Min @ 80 MHz
-10 dB Min. @ 100 MHz
- 4.9 Cross Talk:** -45 dB Min. @ 30 MHz
-40 dB Min. @ 60 MHz
-35 dB Min. @ 100 MHz
- 4.10 Common Mode Rejection :** -43 dB Min. @ 1-30 MHz
-37dB Min. @ 60 MHz
-33dB Min. @ 80-100 MHz
- 4.11 Isolation HI-POT:** 1500Vrms 1mA 1Second

5. Recommended Lead Free IR Reflow Soldering Curve :



Item	Soldertechnique simulation	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350 ± 10 (solder irno temp)	4~5	
2	Vapor phase reflow	215 ± 5 (vapor temp)	60 ± 5	
3	IR/convection reflow	255 ± 5 (component temp)	30 ± 5	1°C/s~4°C/s time above 183°C 90s~120s

Note: The curve includes recommended value only, please adjust your equipment to make sure the solder process.Details please refers to the standard J-STD-020.

6. Reliability Test Criteria:

6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

6.2 Solderbility: Dipped in 245°C+/-5°C molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

6.3 Resistance to soldering heat : Convection reflow condition setting: peak temperature at 260°C+0/-5°C above 217°C for 90-180 seconds, ramp-up rate 2-3°C/s. Ramp-down rate 6°C/s Max. No mechanical problem found. No electrical failure found per our specification.

6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.

6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6.6 Dry heat: 100+/-2°C 96 hours.

6.7 Cold: -20+/-2°C 96 hours.

6.8 Damp Heat: 60+/-2°C, 93+/-3% RH 96 hours.

6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2°C,2-3minutes at 20+/-2°C,30 minutes at 85+/-2°C, 2-3 minutes at 20+/-2°C.